



## Final Product Change Notification

202301009F01 : MC33771B Product Burn-In Elimination On Improved Quality Robustness Silicon Design

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Jan 14, 2023 **Effective date:** Apr 14, 2023

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For detailed information we invite you to view this notification online

### Management summary

Burn-in Elimination from the Final Test production flow for the BCC14 Rev B+ MC33771B products.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

NXP Semiconductors announces the Burn-in elimination from the Final Test production flow for the MC33771B Battery Cell Controller IC products associated with this notification. As previously informed, MC33771B product was migrated to an improved quality robustness design. The burn-in process was originally introduced on MC33771B product to address qualification rejects linked to PMV5 capacitors. The PMV5 capacitors were removed from MC33771B with the enhanced quality design migration.

In order to confirm efficiency of the new design, NXP performed a burn-in study. The burn-in elimination evaluation was successfully completed after testing 100k units from 5 different wafer lots and 12 assembly lots, processed in the same wafer fabrication facility, with zero burn-in related failures.

Upon PCN 202301009F01 approval, the burn-in process will be removed from the Final Test production flow for improved quality design MC33771B products.

Please see the attached files for additional details.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-QG-01

## Reason

The original reason for burn-in implementation (qualification rejects linked to PMV5 capacitors), has been resolved with product migration to improved quality design.

Burn-in elimination can now proceed, and results in optimized manufacturing test flow for reduced cycle time and enhanced product delivery.

## Identification of Affected Products

Product identification does not change

## Product Availability

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### Sample Information

Not Applicable

### Production

Planned first shipment Apr 14, 2023

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

### Disposition of Old Products

Existing inventory will be shipped until depleted

## Additional information

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Self qualification: [view online](#)

Additional documents: [view online](#)

## Timing and Logistics

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In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Feb 13, 2023.

## Contact and Support

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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<b>Position</b>	Quality Engineer
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NXP Quality Management Team.

### About NXP Semiconductors

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
MC33771BTA1AE	935350632557	MC33771BTA1AE	BCC14	H(L)QFP64	SOT1510-2	RFS	No	BLC3
MC33771BTP1AER2	935350893528	MC33771BTP1AER2	BCC14	H(L)QFP64	SOT1510-2	RFS	No	BLC3
MC33771BTA1AER2	935350632528	MC33771BTA1AER2	BCC14	H(L)QFP64	SOT1510-2	RFS	No	BLC3
MC33771BTP1AE	935350893557	MC33771BTP1AE	BCC14	H(L)QFP64	SOT1510-2	RFS	No	BLC3